使るN54ALS541 SN74ALS540 SN74ALS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SDAS025D - APRIL 1982 - REVISED MARCH 2002

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- pnp Inputs Reduce dc Loading
- Data Flowthrough Pinout (All Inputs on Opposite Side From Outputs)

description

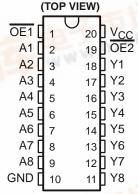
These octal buffers and line drivers are designed to have the performance of the popular SN54ALS240A/SN74ALS240A series and, at the same time, offer a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly facilitates printed circuit board layout.

The 3-state control gate is a 2-input NOR gate such that, if either output-enable (OE1 or OE2) input is high, all eight outputs are in the high-impedance state.

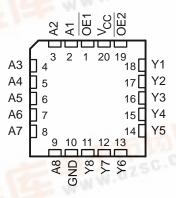
The SN74ALS540 provides inverted data. The 'ALS541 provide true data at the outputs.

The -1 versions of SN74ALS540 and SN74ALS541 are identical to the standard versions, except that the recommended maximum I_{OL} is increased to 48 mA. There is no -1 version of the SN54ALS541.

SN54ALS541 ... J PACKAGE SN74ALS540 ... DW, N, OR NS PACKAGE SN74ALS541 ... DB, DW, N, OR NS PACKAGE



SN54ALS541 ... FK PACKAGE (TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

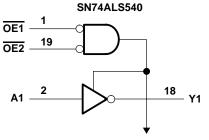


ORDERING INFORMATION

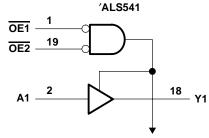
TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
			SN74ALS540N	SN74ALS540N
	PDIP – N	Tube	SN74ALS540-1N	SN74ALS540-1N
	PDIP - N	Tube	SN74ALS541N	SN74ALS541N
			SN74ALS541-1N	SN74ALS541-1N
		Tube	SN74ALS540DW	ALS540
		Tape and reel	SN74ALS540DWR	AL3340
		Tube	SN74ALS540-1DW	ALS540-1
	SOIC – DW	Tube	SN74ALS541DW	ALS541
0°C to 70°C		Tape and reel	SN74ALS541DWR	AL3341
		Tube	SN74ALS541-1DW	ALS541-1
		Tape and reel	SN74ALS541-1DWR	AL3341-1
	SOP – NS	Tape and reel	SN74ALS540NSR	ALS540
			SN74ALS540-1NSR	ALS540-1
	30F - N3	Tape and reel	SN74ALS541NSR	ALS541
			SN74ALS541-1NSR	ALS541-1
	SSOP – DB	Topo and rook	SN74ALS541DBR	G541
	330F - DB	Tape and reel	SN74ALS541-1DBR	G541-1
–55°C to 125°C	CDIP – J	Tube	SNJ54ALS541J	SNJ54ALS541J
-55°C 10 125°C	LCCC – FK Tube		SNJ54ALS541FK	SNJ54ALS541FK

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

logic diagrams (positive logic)



To Seven Other Channels



To Seven Other Channels



SN54ALS541, SN74ALS540, SN74ALS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V _{CC}		 7 V
Input voltage, V _I		
Voltage applied to a disabled 3-state output		
Package thermal impedance, θ _{JA} (see Note 1): DB package	 70°C/W
	DW package	 58°C/W
	N package .	 69°C/W
	NS package	 60°C/W
Storage temperature range, T _{stg}		 -65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			SN54ALS541		SN74ALS540 SN74ALS541			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.7			0.8	V
ЮН	High-level output current				-12			-15	mA
lo	Low lovel output ourrent				12			24	m 1
lOL	Low-level output current							48†	mA
T _A	Operating free-air temperature		-55		125	0		70	°C

[†] Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

SN54ALS541, SN74ALS540, SN74ALS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS541					SN74ALS540 SN74ALS541		
					TYP‡	MAX	MIN	TYP‡	MAX		
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2			
\/o			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		٧	
VOH		V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V	
			I _{OH} = -15 mA				2				
			I _{OL} = 12 mA		0.25	0.4		0.25	0.4		
VOL		V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V	
		I _{OL} = 48 mA [†]					0.35	0.5			
lozh		V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ	
lozL		V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ	
lį		V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA	
lн		V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ	
I _{IL}		$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.2			-0.1	mA	
I _O §		$V_{CC} = 5.5 \text{ V},$	V _O = 2.25 V	-20		-112	-30		-112	mA	
			Outputs high					5	10		
	SN74ALS540	V _{CC} = 5.5 V	Outputs low					13	22		
			Outputs disabled					11	19	mA	
ICC			Outputs high		6	14		6	14		
'ALS541	'ALS541	V _{CC} = 5.5 V	Outputs low		15	25		15	25		
			Outputs disabled		13.5	32		13.5	22		

 $[\]dagger$ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	$\begin{array}{c} \text{V}_{\text{CC}} = 4.5 \text{ V to } 5.5 \text{ V,} \\ \text{C}_{\text{L}} = 50 \text{ pF,} \\ \text{R1} = 500 \ \Omega, \\ \text{TO} \\ \text{R2} = 500 \ \Omega, \\ \text{(OUTPUT)} \\ \end{array}$							UNIT
			SN54ALS541		SN74ALS540		SN74ALS541		
			MIN	MAX	MIN	MAX	MIN	MAX	
^t PLH	А	V	4	17	2	12	4	14	ns
^t PHL	A	Y	2	14	2	9	2	10	115
^t PZH	ŌĒ	V	5	18	5	15	5	15	ns
^t PZL	OE	l Y	8	28	8	20	8	20	115
t _{PHZ}	ŌĒ	V	1	12	1	10	1	10	ns
t _{PLZ}	OE	1	2	14	2	12	2	12	115

[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

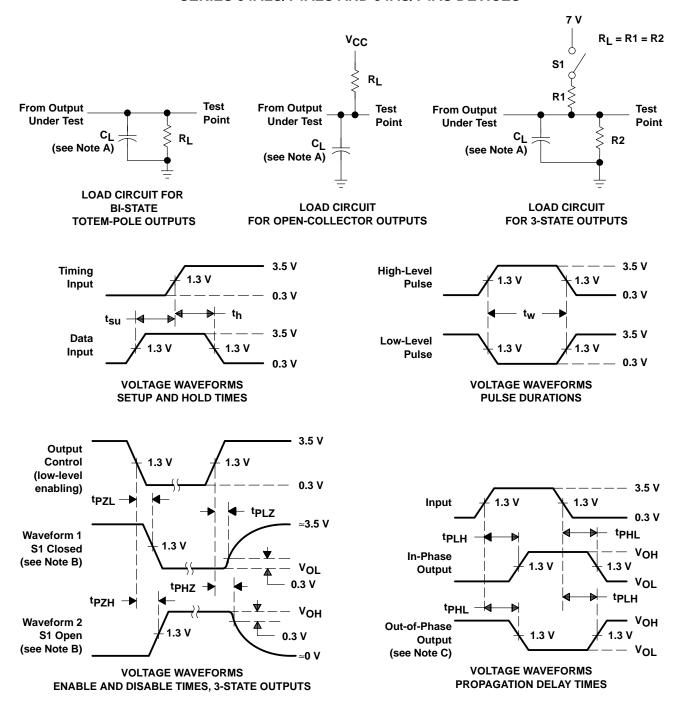


[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

[§] The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-89602012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8960201RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8960201SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
SN54ALS541J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN74ALS540-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540-1DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74ALS540-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS540-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS540-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS540N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74ALS540NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS540NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS540NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541-1DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541-1DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541-1DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC



PACKAGE OPTION ADDENDUM

26-Sep-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS541-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS541-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS541N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74ALS541NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS541NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS541NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS541FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ALS541J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

26-Sep-2005

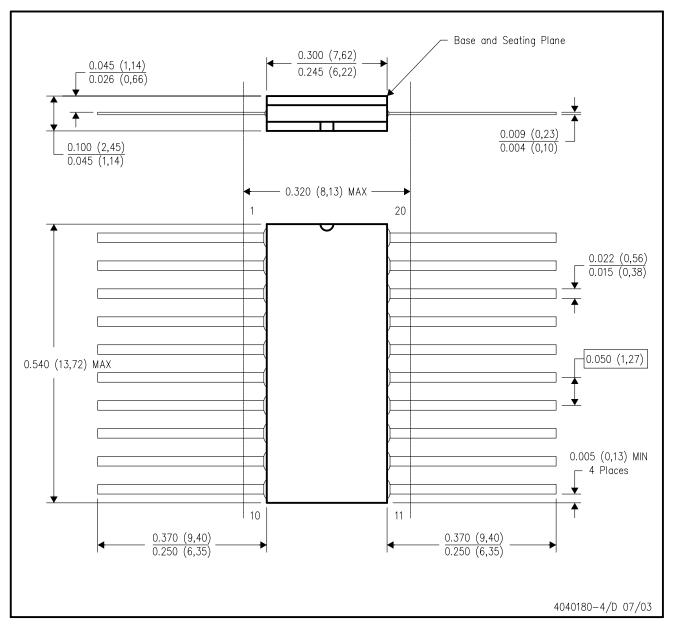
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- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



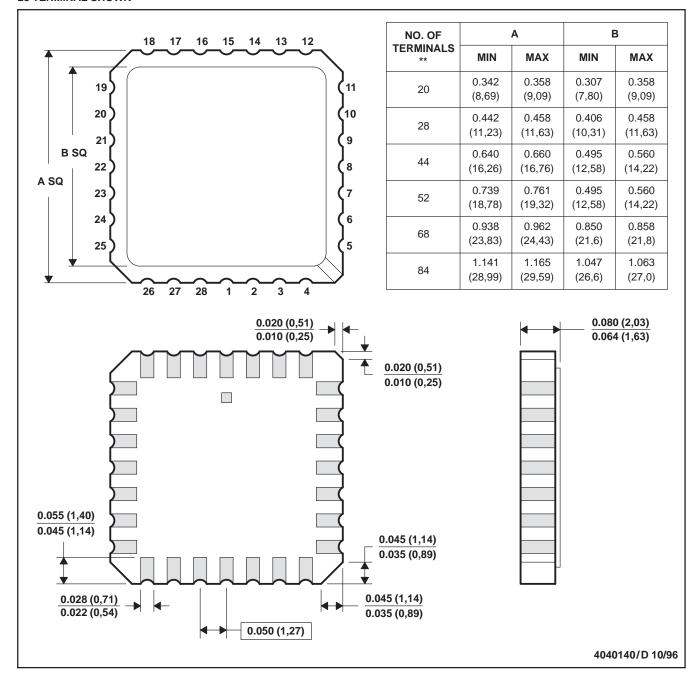
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

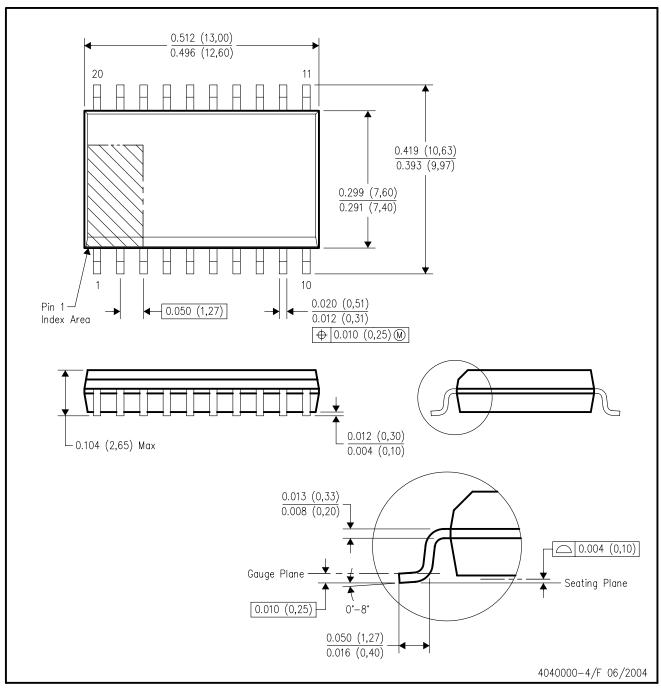
16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- . All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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